

### Primary Characteristics

$I_F$	1.0	A
$V_{RRM}$	50~1000	V
$I_{FSM}$	30	A
$V_F$	1.0	V

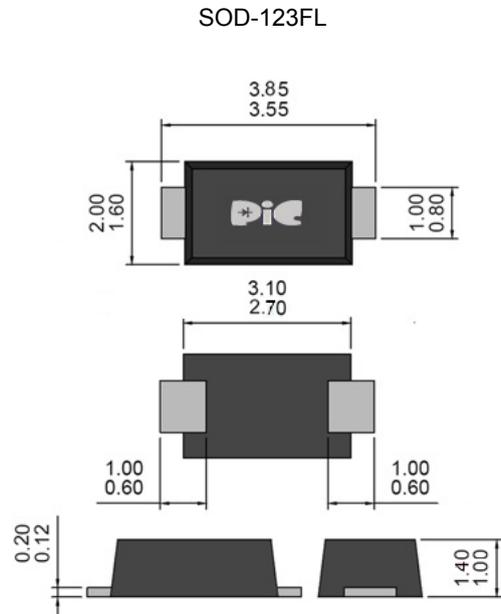
### Features

- For surface mounted applications
- Low profile package
- Ideal for automated placement
- Glass Passivated Chip Junction
- High temperature soldering : 260°C/10 seconds at terminals
- Lead-free & halogen-free parts, RoHS compliant

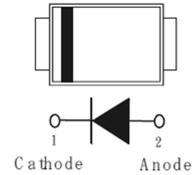
### Mechanical Data

- Epoxy: UL94V-0 rated flame retardant
- Case: Molded Plastic
- Terminals: Solder plated solderable per MIL-STD-750 Method 2026
- Mounting position: Any
- Polarity: Color band denotes cathode end
- Weight: approx.. 0.0166 grams

### Package Outline Dimensions



Unit : millimeters



### Maximum Ratings & Electrical Characteristic

	Symbol	GS1000FL	GS1001FL	GS1002FL	GS1004FL	GS1006FL	GS1008FL	GS1010FL	UNITS
Marking Code	-	1A	1B	1D	1G	1J	1K	1M	-
Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	Volts
RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	Volts
DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	Volts
Average Forward Current (Note 1)	$I_{F(AV)}$	1.0							Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load(JEDEC Method)	$I_{FSM}$	30.0							Amps
Max. Forward Voltage at 1.0A	$V_F$	1.0							Volts
Max. DC Reverse Current $T_J=$ 25°C Rated DC Blocking Voltage	$I_R$	1							$\mu A$
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	65							°C/W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-50 ~ +150							°C

Notes:

- (1) Pulse test: 300u pulse with, 1% duty cycle.
- (2) Soldering land: 6mm x 6mm.

### Rating and Characteristics Curves

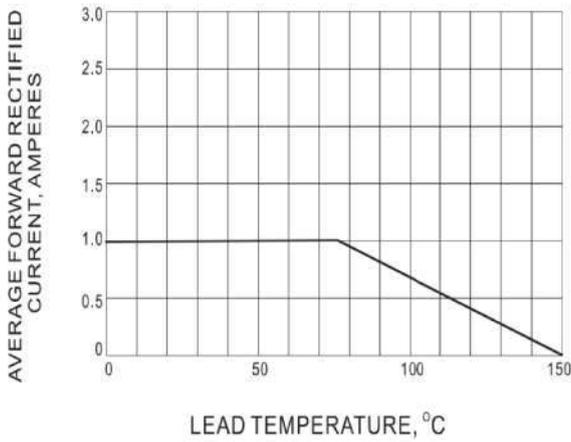


Fig.1 Forward Current Derating Curve

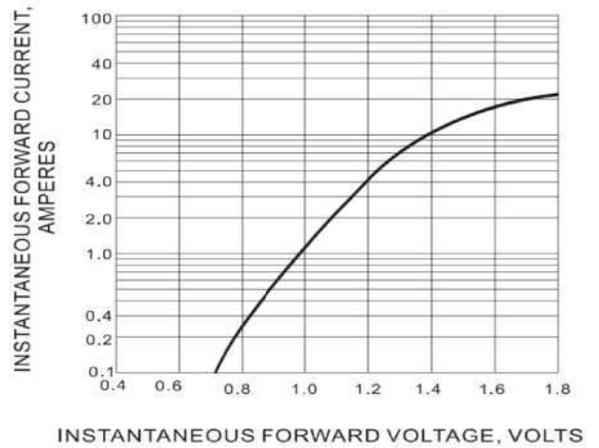


Fig. 2 Typical Instantaneous Forward Characteristics

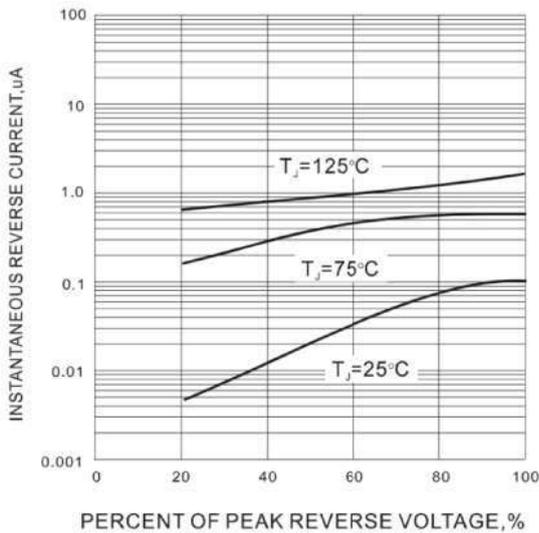


Fig.3 Typical Reverse Characteristics

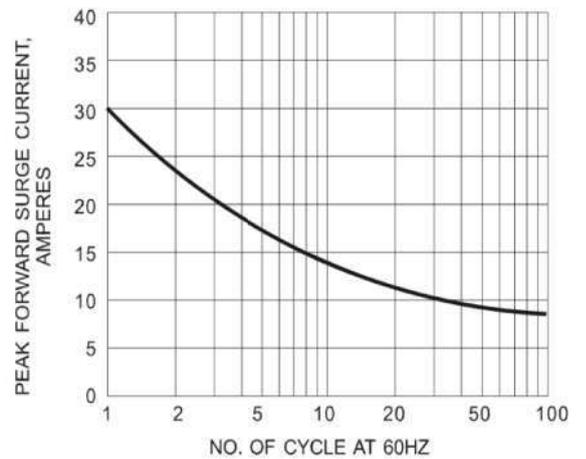
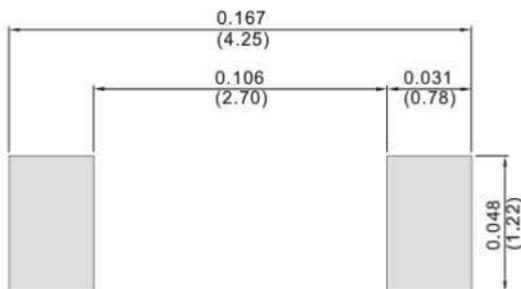


Fig.4 Max. Non- Repetitive Surge Current

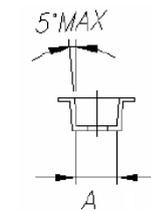
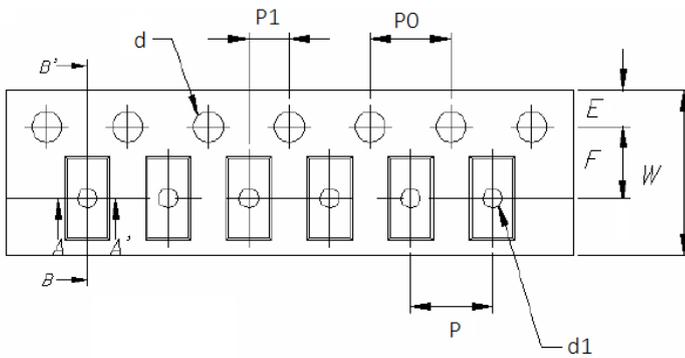
### Pad Layout



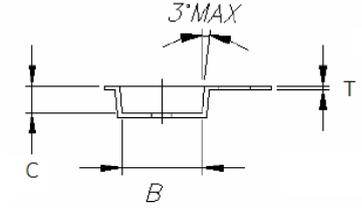
Unit: mm

### Packaging Specifications

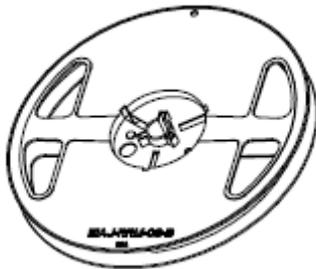
Package	W (mm)	A (mm)	B (mm)	C (mm)	d1 (mm)	d (mm)	E (mm)	F (mm)	P (mm)	P0 (mm)	P1 (mm)	T (mm)
SOD-123FL	8±0.2	2.00±0.1	3.85±0.1	1.1±0.1	1.0	1.50±0.1	1.75±0.1	3.5±0.05	4±0.1	4±0.05	2±0.05	0.23±0.05
SOD-123HE	8±0.3	2.00±0.1	4.00±0.1	1.45±0.1	1.0	1.55±0.1	1.75±0.1	3.5±0.05	4±0.1	4±0.10	2±0.05	0.23±0.10
SOD-323FL	8±0.2	1.37±0.1	2.75±0.1	0.85±0.1	1.00	1.60±0.1	1.75±0.1	3.50±0.05	4±0.1	4±0.10	-	0.20±0.10
SOD-323HE	8±0.3	1.60±0.1	2.80±0.1	0.95±0.1	1.0	1.50±0.1	1.75±0.1	3.5±0.05	4±0.1	4±0.10	2±0.05	0.23±0.10
SMAF	12±0.3	2.9±0.1	5.5±0.1	2.1±0.1	1.5	1.55±0.1	1.75±0.1	5.5±0.05	4±0.1	4±0.10	2±0.05	0.23±0.10
SMA-S	12±0.2	2.65±0.1	5.25±0.1	1.35±0.1	1.0	1.55±0.1	1.75±0.1	5.5±0.05	4±0.1	4±0.05	2±0.05	0.23±0.10
SMA-HE	12±0.2	2.65±0.1	5.25±0.1	1.35±0.1	1.0	1.55±0.1	1.75±0.1	5.5±0.05	4±0.1	4±0.05	2±0.05	0.23±0.10



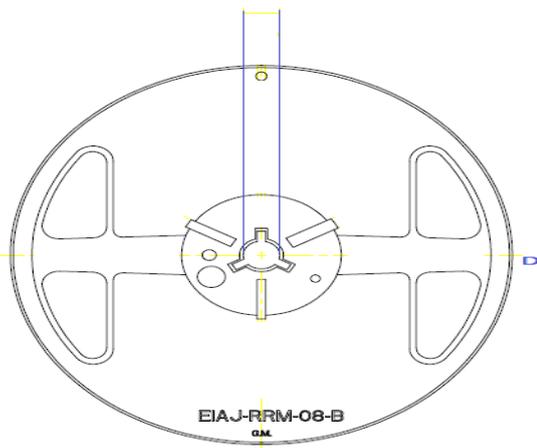
SECTION A-A'



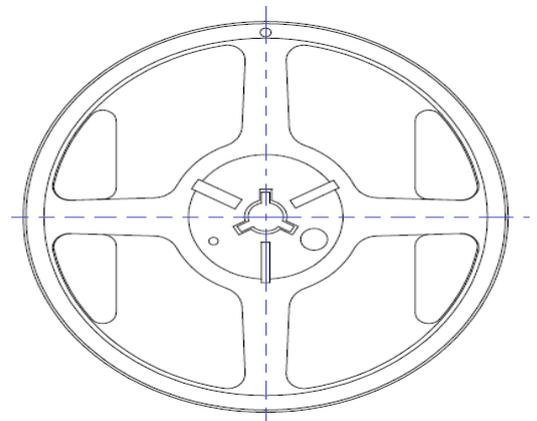
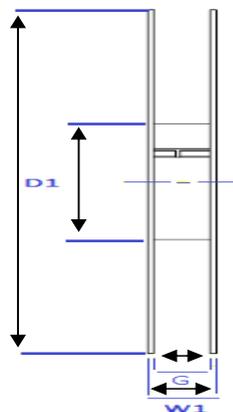
SECTION B-B'



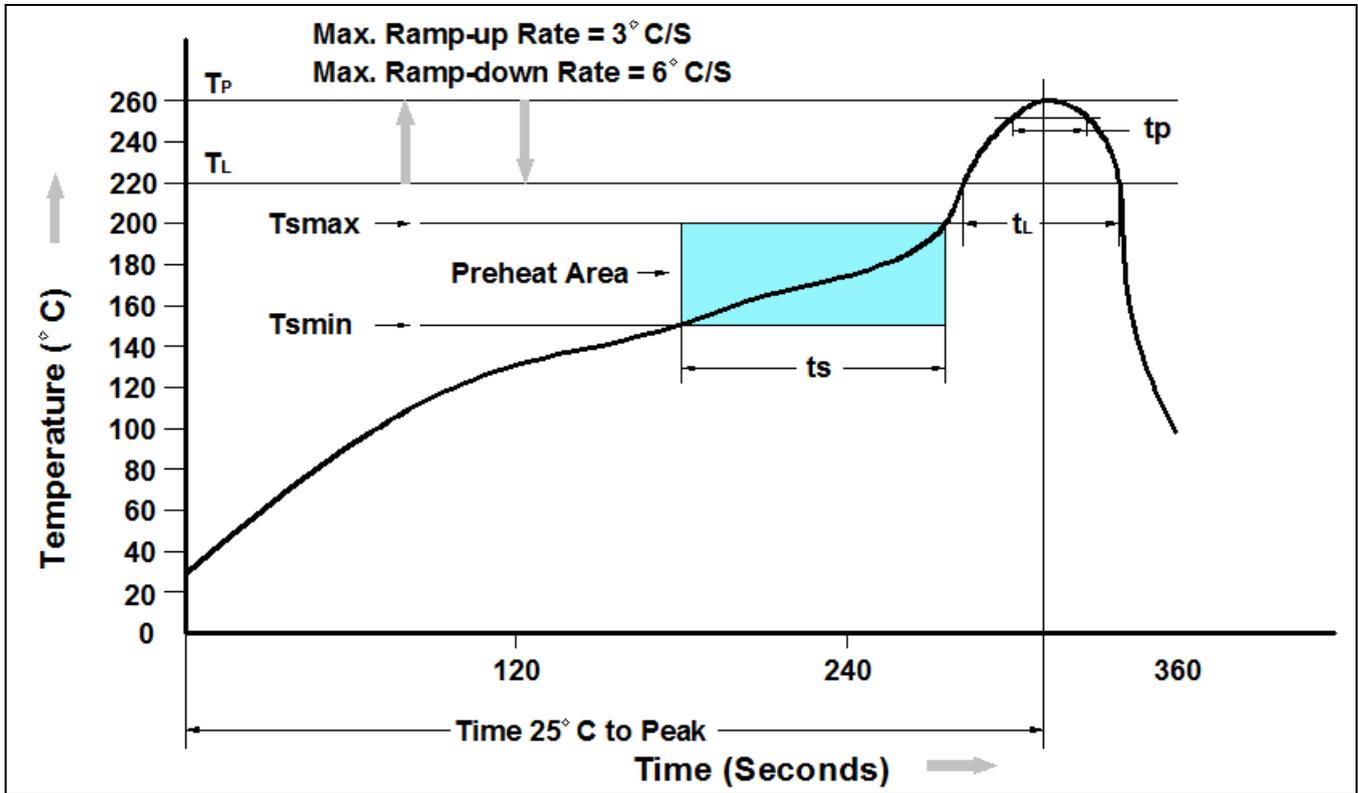
Package	D (max.) (mm)	D1 (min.) (mm)	D2 (mm)	G (min.) (mm)	W1 (min.) (mm)
SOD-123FL	178	50.0	13.0±0.2	8.4	11.4
SOD-123HE	178	50.0	13.0±0.2	8.4	11.4
SOD-323FL	178	50.2	13.0±0.2	8.0	11.5
SOD-323HE	178	50.0	13.0±0.2	8.4	11.4
SMAF	178	50.0	13.0±0.2	12.4	18.0
	330	50.0	13.0±0.2	12.4	18.0
SMA-S	178	50.0	13.0±0.2	12.4	18.0
SMA-HE	178	50.0	13.0±0.2	12.4	18.0



EIAJ-RPM-08-B  
QML



### Recommend IR Reflow Soldering Thermal Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds
Average Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

### Ordering Information

Part Number	Description	Quantity
GS1000FL~GS1010FL	SOD-123FL Reel	3000 pcs

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